

D₁
Cont

a metal thin film resistive layer directly attached to the substrate, the metal thin film layer being non-tantalum;
a chip resistor termination attached on each end of the metal thin film resistive layer; and
an outer moisture barrier consisting of tantalum pentoxide directly overlaying and attaching to the metal thin film resistive layer for reducing failures due to electrolytic corrosion under powered moisture conditions.

13. (Thrice Amended)

D₂

A nickel-chromium alloy thin film chip resistor comprising:
a substrate;
a nickel-chromium alloy thin film layer directly attached to the substrate;
a chip resistor termination attached on each end of the nickel-chromium alloy thin film; and
an outer moisture barrier consisting of tantalum pentoxide directly overlaying and attaching to the nickel-chromium alloy thin film layer for reducing failures due to electrolytic corrosion under powered moisture conditions.

D₃

15. Twice Amended)

A nickel-chromium alloy thin film resistor comprising:
a substrate;
a nickel-chromium alloy thin film layer directly attached to the substrate;
a passivation layer directly overlaying and attaching to the nickel-chromium alloy layer; and
an outer moisture barrier consisting of tantalum pentoxide directly overlaying and attaching to the passivation layer for reducing failures due to electrolytic corrosion under powered moisture conditions.

16. (Amended)

A thin film resistor comprising:

a resistor substrate;

a metal thin film resistive layer directly attached to the substrate, the metal thin film layer being

non-tantalum;

a chip resistor termination attached on each end of the metal thin film resistive layer;

a passivation layer directly overlaying the metal thin film resistive layer;

an outer moisture barrier consisting of tantalum pentoxide directly overlaying the passivation

layer for reducing failures due to electrolytic corrosion under powered moisture

conditions.